



Semiconductor Materials Information

CMP CONSUMABLES

2008

A Techcet Group
Critical Materials Report

PREPARED BY

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Techcet Group's 2008 Critical Materials Report on CMP Consumables is the **most comprehensive market report** on CMP materials found anywhere today. Through Techcet's strong industry contacts and technical expertise, the 2008 report has far **surpassed expectations**. Not only does this report cover market **drivers and statistics** (size, share, growth, etc.) for **CMP slurries and pads**, including market share per slurry category, and pad forecast by revenue and unit volume, but it also includes market information on **post CMP cleaning and CMP ancillaries, such as pad conditioners, slurry filters, and PVA brushes**. This year's report also includes a discussion on the **cost contribution of CMP materials**. In addition, **information on more than 150 suppliers** of the various materials and equipment suppliers that compete in the CMP market space is provided in this year's report. For more details, please see the following table of contents. To order, simply complete the attached order form, or call Techcet Group at 775-783-8180.

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